

REMARKS

Title

The Examiner has stated that the title of the invention is not descriptive.

Applicant submits herewith an amended title of the invention that is clearly indicative of the invention to which the claims are directed.

Drawings

The Examiner has requested formal drawings.

Applicant includes herewith formal drawings.

Claim Rejections 35 U.S.C. § 112, second paragraph

The Examiner has rejected claims 2-5, 14, and 15 under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which Applicant regards as the invention.

Applicant has amended claims 2-5 and 14 to more particularly point out and distinctly claim the subject matter which Applicant regards as the invention.

Claim Rejections 35 U.S.C. § 102 (b)

The Examiner has rejected claims 1-4, 6, 7, 11, 12, 14, 15, and 26-28 under 35 U.S.C. § 102 (b) as being anticipated by Kim (US 5,854,513).

Applicant respectfully disagrees with the Examiner. The Kim reference cited by the Examiner shows a BLM (25), with one segment, that is located over two bond pads (22, 23). See Figures 3-6. A bump (27) is located over the BLM (25).

However, an embodiment of Applicant's invention, as claimed in claim 1, claims a BLM (24), with two (or more) segments (24N, 24N), that is located over one bond pad (21b). See Figure 2a and lines 15-16 on page 6 of the specification. A bump (25) is located over the BLM (24).

The Kim reference cited by the Examiner does not teach each and every element of Applicant's invention. Consequently, Kim does not anticipate claim 1 of Applicant's invention. Claims 2-4, 6, 7, 11, 12, 14, and 15 are dependent on claim 1 and, thus, are also not anticipated by Kim.

Another embodiment of Applicant's invention, as claimed in claim 26, claims a bond pad with two (or more) segments, and a wire lead that is attached to the two (or more) segments.

The Kim reference cited by the Examiner does not teach a wire lead. The Kim reference cited by the Examiner does not teach each and every element of Applicant's invention. Consequently, Kim does not anticipate claim 26 of Applicant's invention. Claims 27-28 are dependent on claim 26 and, thus, are also not anticipated by Kim.

Claim Rejections 35 U.S.C. § 103 (a)

The Examiner has rejected claims 5, 8-10, and 13 under 35 U.S.C. §103 (a) as being unpatentable over Kim (US 5,854,513) and Fukuda et al. (Kokai 05-013418).

Applicant respectfully disagrees with the Examiner. As discussed previously, the Kim reference cited by the Examiner does not teach segmented BLM at all. Consequently, claim 1 would not have been obvious to one of ordinary skill in the art at the time the invention was made. Claims 5, 8-10, and 13 are dependent on claim 1. Thus, combination of Kim and Fukuda et al. will not produce Applicant's invention, as claimed in claims 5, 8-10, and 13, and Applicant's invention, as claimed in claims 5, 8-10, and 13 would also not have been obvious to one of ordinary skill in the art at the time the invention was made.

Consequently, Applicant submits that the two references cited by the Examiner do not teach, suggest, or render obvious the invention as claimed by Applicant. In view of the foregoing, Applicant respectfully requests the Examiner to withdraw the rejections to claims 5, 8-10, and 13 under 35 U.S.C. §103 (a).

Conclusion

Applicant believes that all claims pending, including amended claims, are now in condition for allowance so such action is earnestly solicited at the earliest possible date.

VERSION WITH MARKINGS TO SHOW CHANGES MADE

2. (Once Amended) The device of claim 1 wherein said bump comprises a a LeadTin (Pb-Sn) solder [such as Lead-Tin (Pb-Sn) or Lead-Indium (Pb-In)].
3. (Once Amended) The device of claim 1 wherein said bump is free of [does not comprise] Lead (Pb).
4. (Once Amended) The device of claim 1 wherein said bump comprises a Tin-Silver-Copper (Sn-Ag-Cu) ternary alloy [such as Tin-Silver-Copper (Sn-Ag-Cu)].
5. (Once Amended) The device of claim 1 wherein said bump comprises an Electrically Conductive Adhesive (ECA) [or polymer].
14. (Once Amended) The device of claim 4, [further comprising bond pads,] wherein each of said segments [a segment] is electrically connected to two or more of said bond pads.